

# BYV410-600

## Enhanced ultrafast dual rectifier diode

Rev. 01 — 29 June 2009

Product data sheet

## 1. Product profile

### 1.1 General description

Enhanced ultrafast dual rectifier diode in a SOT78 (TO-220AB) plastic package.

### 1.2 Features and benefits

- High thermal cycling performance
- Low on state losses
- Low thermal resistance
- Soft recovery characteristic minimizes power consuming oscillations

### 1.3 Applications

- Dual mode (DCM and CCM) PFC
- Power Factor Correction (PFC) for Interleaved Topology

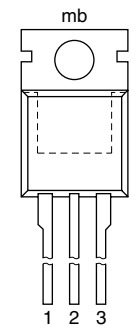
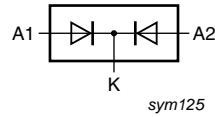
### 1.4 Quick reference data

Table 1. Quick reference

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{RRM}$	repetitive peak reverse voltage		-	-	600	V
$I_{O(AV)}$	average output current	square-wave pulse; $\delta = 0.5$ ; $T_{mb} \leq 92\text{ °C}$ ; both diodes conducting; see <a href="#">Figure 1</a> ; see <a href="#">Figure 2</a>	-	-	20	A
<b>Dynamic characteristics</b>						
$t_{rr}$	reverse recovery time	$I_F = 1\text{ A}$ ; $V_R = 30\text{ V}$ ; $dI_F/dt = 100\text{ A}/\mu\text{s}$ ; $T_j = 25\text{ °C}$ ; see <a href="#">Figure 5</a>	-	20	35	ns
$Q_r$	recovered charge	$I_F = 1\text{ A}$ ; $V_R = 30\text{ V}$ ; $dI_F/dt = 100\text{ A}/\mu\text{s}$	-	15	28	C
<b>Static characteristics</b>						
$V_F$	forward voltage	$I_F = 10\text{ A}$ ; $T_j = 150\text{ °C}$	-	1.3	1.9	V
		$I_F = 10\text{ A}$ ; $T_j = 25\text{ °C}$ ; see <a href="#">Figure 4</a>	-	1.4	2.1	V

## 2. Pinning information

**Table 2. Pinning information**

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	A1	anode 1		
2	K	cathode		
3	A2	anode 2		
mb	K	mounting base; cathode		

**SOT78  
(TO-220AB)**

## 3. Ordering information

**Table 3. Ordering information**

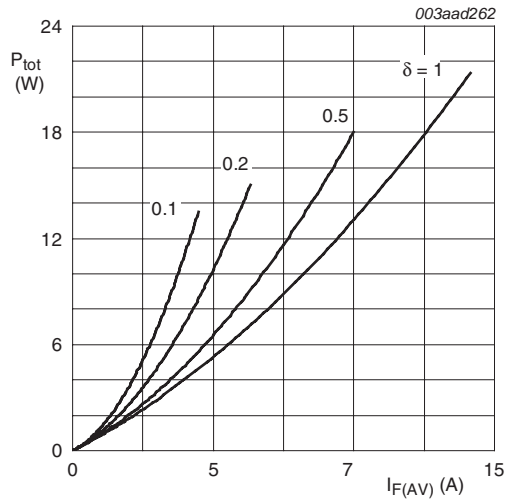
Type number	Package		Version
	Name	Description	
BYV410-600	TO-220AB	plastic single-ended package; heatsink mounted; 1 mounting hole; 3-lead TO-220AB	SOT78

## 4. Limiting values

**Table 4. Limiting values**

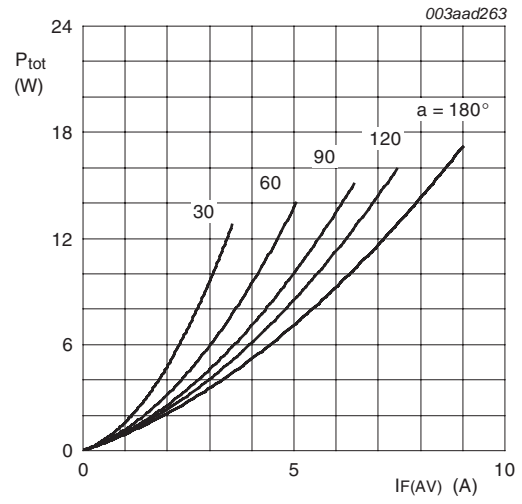
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{RRM}$	repetitive peak reverse voltage		-	600	V
$V_{RWM}$	crest working reverse voltage		-	600	V
$V_R$	reverse voltage	DC	-	600	V
$I_{O(AV)}$	average output current	square-wave pulse; $\delta = 0.5$ ; $T_{mb} \leq 92$ °C; both diodes conducting; see <a href="#">Figure 1</a> ; see <a href="#">Figure 2</a>	-	20	A
$I_{FRM}$	repetitive peak forward current	$\delta = 0.5$ ; $t_p = 25$ $\mu$ s; $T_{mb} \leq 108$ °C; per diode	-	20	A
$I_{FSM}$	non-repetitive peak forward current	$t_p = 8.3$ ms; sine-wave pulse; $T_{j(init)} = 25$ °C; per diode	-	132	A
		$t_p = 10$ ms; sine-wave pulse; $T_{j(init)} = 25$ °C; per diode	-	120	A
$T_{stg}$	storage temperature		-40	150	°C
$T_j$	junction temperature		-	150	°C



$$I_{F(AV)} = I_{F(RMS)} \times \sqrt{\delta}$$

**Fig 1. Forward power dissipation as a function of average forward current; square waveform; maximum values**



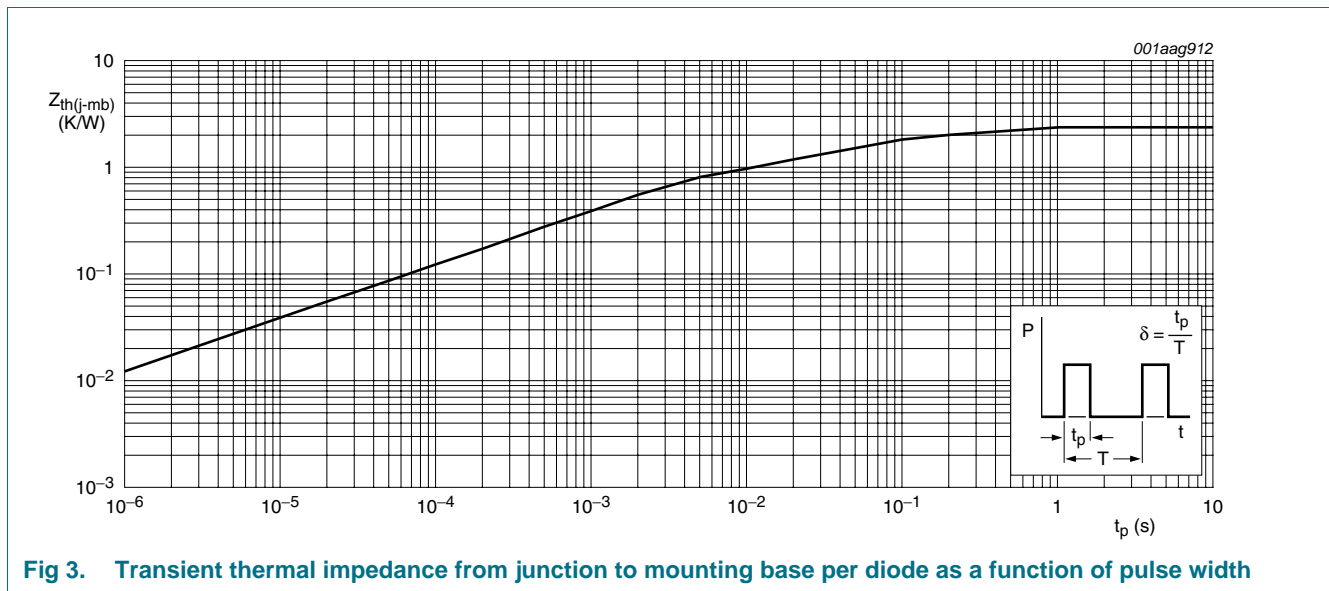
$$a = \text{form factor} = I_{T(RMS)} / I_{T(AV)}$$

**Fig 2. Forward power dissipation as a function of average forward current; sinusoidal waveform; maximum values**

### 5. Thermal characteristics

Table 5. Thermal characteristics

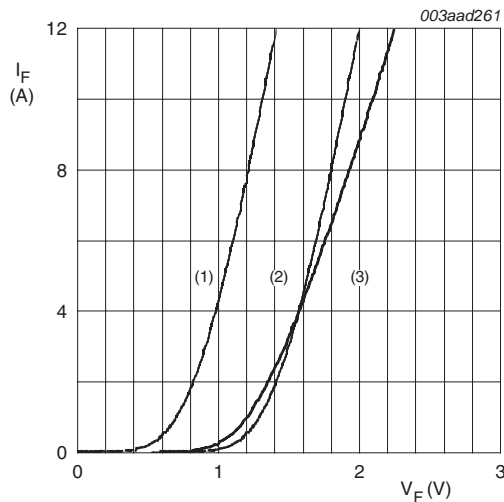
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	with heatsink compound; per diode; see <a href="#">Figure 3</a>	-	-	2.4	K/W
		with heatsink compound; both diodes conducting	-	-	1.6	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient		-	60	-	K/W



## 6. Characteristics

Table 6. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Static characteristics</b>						
$V_F$	forward voltage	$I_F = 10\text{ A}; T_j = 150\text{ °C}$	-	1.3	1.9	V
		$I_F = 10\text{ A}; T_j = 25\text{ °C};$ see <a href="#">Figure 4</a>	-	1.4	2.1	V
$I_R$	reverse current	$V_R = 600\text{ V}$	-	13	50	$\mu\text{A}$
		$V_R = 600\text{ V}; T_j = 100\text{ °C}$	-	1	1.5	mA
<b>Dynamic characteristics</b>						
$Q_r$	recovered charge	$I_F = 1\text{ A}; V_R = 30\text{ V}; dI_F/dt = 100\text{ A}/\mu\text{s}$	-	15	28	C
$t_{rr}$	reverse recovery time	$I_F = 1\text{ A}; V_R = 30\text{ V}; dI_F/dt = 100\text{ A}/\mu\text{s}; T_j = 25\text{ °C};$ see <a href="#">Figure 5</a>	-	20	35	ns
$I_{RM}$	peak reverse recovery current	$I_F = 1\text{ A}; V_R = 30\text{ V}; dI_F/dt = 100\text{ A}/\mu\text{s};$ see <a href="#">Figure 5</a>	-	1.4	1.9	A
$V_{FR}$	forward recovery voltage	$I_F = 1\text{ A}; dI_F/dt = 100\text{ A}/\mu\text{s};$ see <a href="#">Figure 6</a>	-	3.2	-	V



- (1)  $T_j = 150\text{ °C}$ ; typical values
- (2)  $T_j = 150\text{ °C}$ ; maximum values
- (3)  $T_j = 25\text{ °C}$ ; maximum values

Fig 4. Forward current as a function of forward voltage

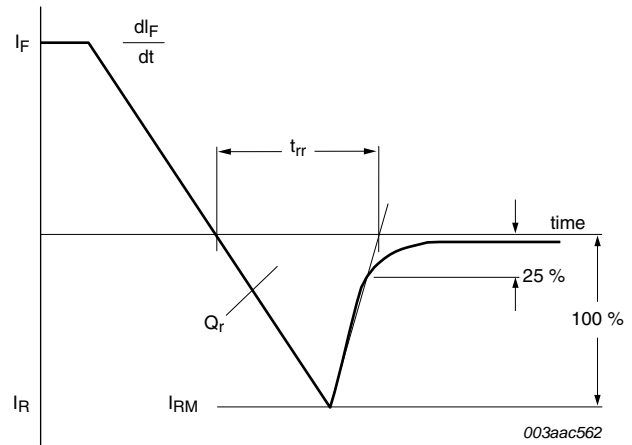


Fig 5. Reverse recovery definitions; ramp recovery

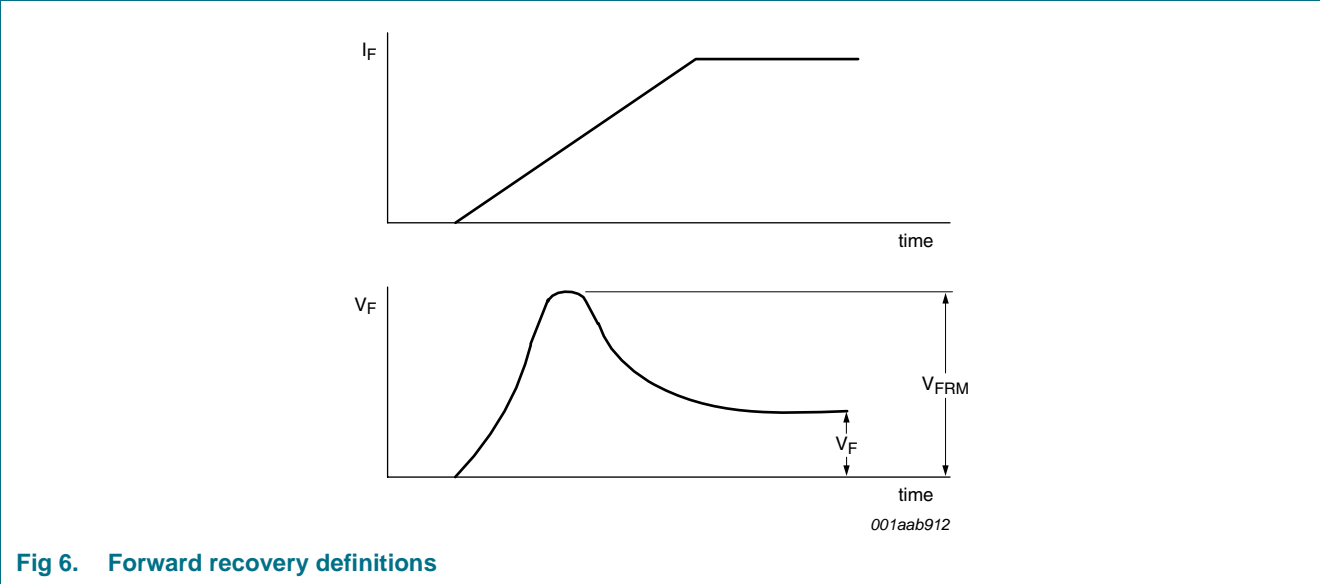


Fig 6. Forward recovery definitions

7. Package outline

Plastic single-ended package; heatsink mounted; 1 mounting hole; 3-lead TO-220AB

SOT78

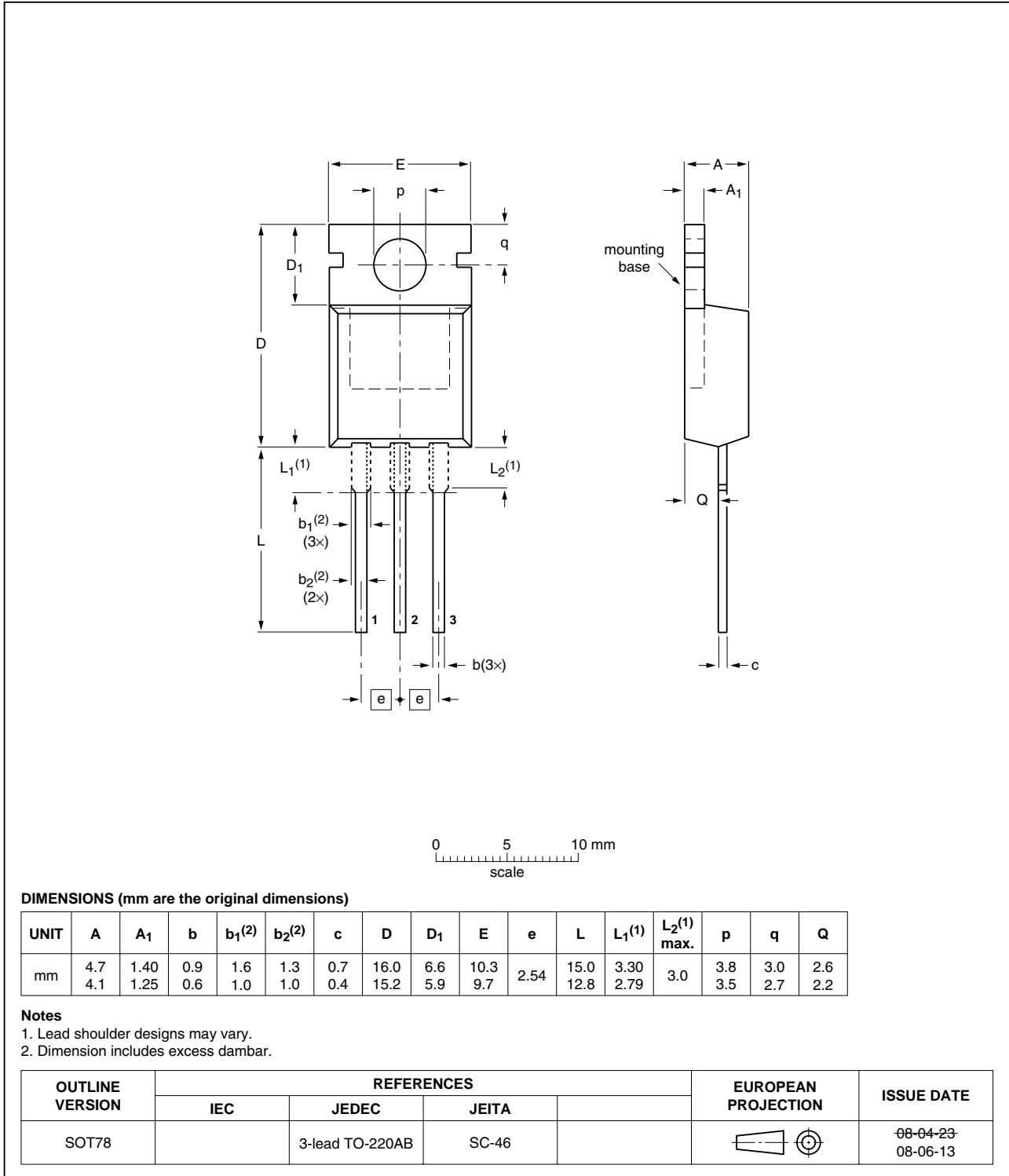


Fig 7. Package outline SOT78 (TO-220AB)

## 8. Revision history

Table 7. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BYV410-600_1	20090629	Product data sheet	-	-



## 9. Legal information

### 9.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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